### MICROCHIP TECHNOLOGY INC

# 28C17A

### 16K (2K x 8) CMOS Electrically Erasable PROM

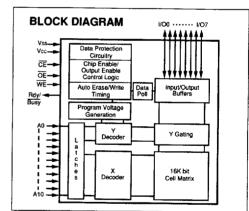
#### **FEATURES**

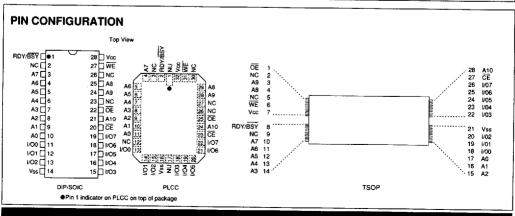
- · Fast Read Access Time-150ns
- CMOS Technology for Low Power Dissipation
  - -30mA Active
  - -100μA Standby
- Fast Byte Write Time—200µs or 1ms
- · Data Retention >10 years
- High Endurance Minimum 10<sup>4</sup> Erase/Write Cycles
- Automatic Write Operation
  - -Internal Control Timer
  - -Auto-Clear Before Write Operation
  - -On-Chip Address and Data Latches
- Data Polling
- Ready/Busy
- Chip Clear Operation
- Enhanced Data Protection
  - -VCC Detector
  - -Pulse Filter
  - -Write Inhibit
- · Electronic Signature for Device Identification
- 5-Volt-Only Operation
- Organized 2Kx8 JEDEC Standard Pinout
- -28 Pin Dual-In-Line Package
- -32-Pin Chip Carrier (Leadless or Plastic)
- -28-Pin Thin Small Outline Package (TSOP)
- Available for Extended Temperature Ranges:
  - —Commercial: 0° C to 70° C
  - -Industrial: -40° C to 85° C

#### DESCRIPTION

The Microchip Technology Inc.'s 28C17A is a CMOS 16K non-volatile electrically Erasable and Programmable Read Only Memory. The 28C17A is accessed like a static RAM for the read or write cycles without the

need of external components. During a "byte write", the address and data are latched internally, freeing the microprocessor address and data bus for other operations. Following the initiation of write cycle, the device will go to a busy state and automatically clear and write the latched data using an internal control timer. To determine when the write cycle is complete, the user has a choice of monitoring the Ready/Busy output or using Data polling. The Ready/Busy pin is an open drain output, which allows easy configuration in wired-or systems. Alternatively, Data polling allows the user to read the location last written to when the write operation is complete. CMOS design and processing enables this part to be used in systems where reduced power consumption and reliability are required. A complete family of packages is offered to provide the utmost flexibility in applications.





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# ELECTRICAL CHARACTERISTICS MAXIMUM RATINGS\*

Vcc and input voltages w.r.t. Vss .	0.6V to + 6.25V
Voltage on OE w.r.t. Vss	0.6V to +13.5V
Voltage on A9 w.r.t. Vss	
Output Voltage w.r.t. Vss	0.6V to Vcc+0.6V
Storage temperature	65° C to 125° C
Ambient temp, with power applied	50° C to 95° C

"Notice: Stresses above those listed under "Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

PIN FUNCTION TABLE							
Name	Function						
A0 - A10 CE OE WE I/O0 - I/O7 RDY/Busy Vcc Vss NC	Address Inputs Chip Enable Output Enable Write Enable Data Inputs/Outputs Ready/Busy +5V Power Supply Ground No Connect; No Internal Connection Not Used; No External						

## READ / WRITE OPERATION DC Characteristics

 $Vcc = +5V \pm 10\%$ 

Commercial (C): Tamb= 0° C to 70° C

Industrial (I): Tamb= -40° C to 85° C

Parameter	Status	Symbol	Min	Max	Units	Conditions
Input Voltages	Logic "1" Logic "0"	VIH VIL	2.0 -0.1	Vcc+1 0.8	V V	
Input Leakage		lu	-10	10	μA	VIN = -0.1V to VCC+1
Input Capacitance		Cin		10	pF	VIN = 0V; Tamb = 25° C; f = 1 MHz
Output Voltages	Logic "1" Logic "0"	Vон Vol	2.4	0.45	V V	IOH = -400μA IOL = 2.1mA
Output Leakage		lLO	-10	10	μА	Vout = -0.1V to Vcc+0.1V
Output Capacitance		Соит		12	рF	Vin = 0V; Tamb = 25° C; f = 1 MHz
Power Supply Current, Active	TTL input	lcc		30	mA	f = 5 MHz (Note 1) Vcc = 5.5V;
Power Supply Current, Standby	TTL input TTL input CMOS input	ICC(S)TTL ICC(S)TTL ICC(S)CMOS		2 3 100	mA mA μA	<u>CE</u> = ViH (0° C to 70° C) <u>CE</u> = ViH (-40° C to 85° C) <u>CE</u> = Vcc-0.3 to Vcc+1

Note: (1) AC power supply current above 5 MHz: 1 mA/MHz

**READ OPERATION AC Characteristics** 

AC Testing Waveform:

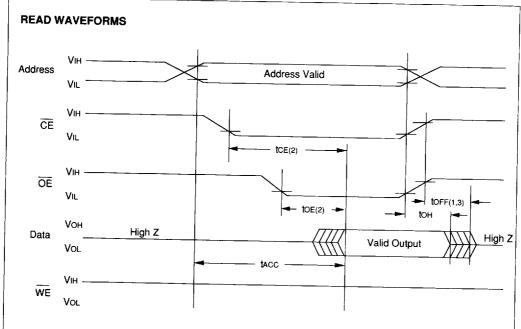
 $V_{IH} = 2.4V$ ;  $V_{IL} = 0.45V$ ;  $V_{OH} = 2.0V$ ;  $V_{OL} = 0.8V$ 

Output Load: 1 TTL Load + 100 pF

Input Rise and Fall Times: 20 nsec Ambient Temperature:

Commercial (C): Tamb = 0° C to 70° C (I): Tamb = -40° C to 85° C Industrial

Parameter	er Sym 28C17A-15 28C17A-20 28C17A		7A-25 Units		Conditions				
	<u> </u>	Min	Max	Min	Max	Min	Max		
Address to Output Delay	tacc		150		200		250	пѕ	OE = CE = VIL
CE to Output Delay	tCE		150		200		250	ns	OE = VIL
OE to Output Delay	tOE		70		80		100	ns	CE = VIL
CE or OE High to Output Float	tOFF	0	50	0	55	0	70	ns	
Output Hold from Address, $\overline{CE}$ or $\overline{OE}$ , whichever occurs first.	tон	0		0		0		ns	



Notes: (1) toff is specified for OE or CE, whichever occurs first

(2) OE may be delayed up to tce - toe after the falling edge of CE without impact on tce

(3) This parameter is sampled and is not 100% tested

**BYTE WRITE AC Characteristics**  AC Testing Waveform: VIH = 2.4V and VIL = 0.45V; VOH = 2.0V; VOL = 0.8V

1 TTL Load + 100 pF Output Load:

Input Rise/Fall Times: 20 nsec

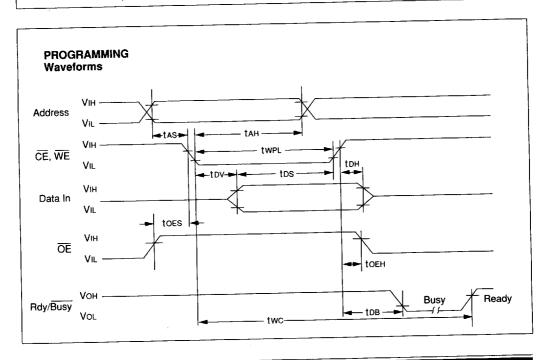
Ambient Temperature: Commercial (C): Tamb = 0° C to 70° C

Industrial (I): Tamb = -40° C to 85° C

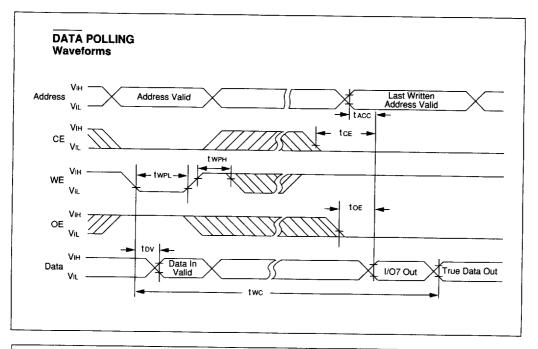
arameter	Symbol	Min	Max	Units	Remarks
ddress Set-Up Time	tas	10		ns	
ddress Hold Time	tan	50		ns	
Pata Set-Up Time	tos	50		ns	
Data Hold Time	ton	10		ns	
Vrite Pulse Width	twpL	100		ns	Note 1
Vrite Pulse High Time	twpH	50		пѕ	
E Hold Time	toeh	10		ns	
DE Set-Up Time	toes	10		ns	
Data Valid Time	tov		1000	ns	Note 2
ime to Device Busy	tos	2	50	ns	
Vrite Cycle Time (28C17A)	twc		1	ms	0.5 ms typical
Write Cycle Time (28C17AF)	twc		200	μs	100μs typical

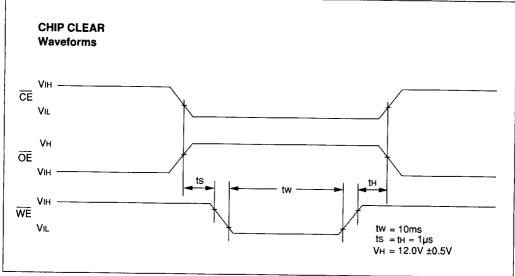
Note: (1) A write cycle can be initiated be  $\overline{CE}$  or  $\overline{WE}$  going low, whichever occurs last. The data is latched on the positive edge of CE or WE, wichever occurs first.

(2) Data must be valid within 1000ns max. after a write cycle is initiated and must be stable at least until tDH after the positive edge of WE or CE, whichever occurs first.



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SUPPLEMENTARY CONTROL								
Mode	CE	OE	WE	A9	Vcc	I/Oı		
Chip Clear	VIL	VH	VIL	X	Vcc	1/01		
Extra Row Read	VIL	VIL	VIH	A9 = VH	Vcc	Data Out		
Extra Row Write	*	VIH	*	A9 = VH	Vcc	Data In		
Note: VH = 12.0V ±0.5V	* Puls	ed per prog	ramming w		100	Data III		

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#### **DEVICE OPERATION**

The Microchip Technology Inc 28C17A has four basic modes of operation—read, standby, write inhibit, and byte write—as outlined in the following table.

Operation Mode	CE	ŌE	WE	1/0	Rdy/Busy(1)		
Read Standby Write Inhibit Write Inhibit Write Inhibit Byte Write	LHHXXL	TXXLXI	H X X H L	Dout High Z High Z High Z High Z Din	H H		
Byte Clear	Automatic Before Each "Write"						

Note: (1) Open drain output. (2) X = Any TTL level.

#### **Read Mode**

The 28C17A has two control functions, both of which must be logically satisfied in order to obtain data at the outputs. Chip enable  $(\overline{CE})$  is the power control and should be used for device selection. Output Enable  $(\overline{OE})$  is the output control and is used to gate data to the output pins independent of device selection. Assuming that addresses are stable, address access time (tACC) equal to the delay from  $\overline{CE}$  to output (tCE). Data is available at the output toE after the falling edge of  $\overline{OE}$ , assuming that  $\overline{CE}$  has been low and addresses have been stable for at least tACC-tOE.

#### Standby Mode

The 28C17A is placed in the standby mode by applying a high signal to the  $\overline{CE}$  input. When in the standby mode, the outputs are in a high impedance state, independent of the  $\overline{OE}$  input.

#### **Data Protection**

In order to ensure data integrity, especially during critical power-up and power-down transitions, the following enhanced data protection circuits are incorporated:

First, an internal Vcc detect (3.3 volts typical) will inhibit the initiation of non-volatile programming operation when Vcc is less than the Vcc detect circuit trip. Second, there is a WE filtering circuit that prevents WE pulses of less than 10ns duration from initiating a write cycle.

Third, holding  $\overline{WE}$  or  $\overline{CE}$  high or  $\overline{OE}$  low, inhibits a write cycle during power-on and power-off (Vcc).

#### Write Mode

The 28C17A has a write cycle similar to that of a Static RAM. The write cycle is completely self-timed and initiated by a low going pulse on the WE pin. On the falling edge of WE, the address information is latched. On rising edge, the data and the control pins (CE and OE) are latched. The Ready/Busy pin goes to a logic low level indicating that the 28C17A is in a write cycle which signals the microprocessor host that the system bus is free for other activity. When Ready/Busy goes back to a high, the 28C17A has completed writing and is ready to accept another cycle.

#### Data Polling

The 28C17A features Data polling to signal the completion of a byte write cycle. During a write cycle, an attempted read of the last byte written results in the data complement of I/O7 (I/O0 to I/O6 are indeterminable). After completion of the write cycle, true data is available. Data polling allows a simple read/compare operation to determine the status of the chip eliminating the need for external hardware.

#### **Electronic Signature for Device Identification**

An extra row of 32 bytes of EEPROM memory is available to the user for device identification. By raising A9 to 12V ±0.5V and using address locations 7EO to 7FF, the additional bytes can be written to or read from in the same manner as the regular memory array.

#### Chip Clear

All data may be cleared to 1's in a chip clear cycle by raising  $\overline{OE}$  to 12 volts and bringing the  $\overline{WE}$  and  $\overline{CE}$  low. This procedure clears all data, except for the extra row.

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#### **SALES AND SUPPORT**

To order or to obtain information, e.g., on pricing or delivery, please use the listed part numbers, and refer to the factory or the listed sales offices.

